

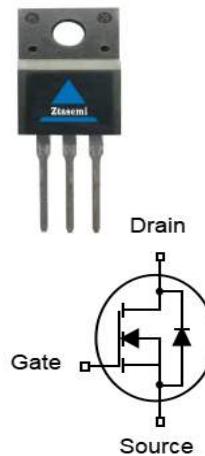


## Features

- N-Channel
- Low  $R_{DS(on)}$
- Low gate charge (typ.  $Q_g = 41.9 \text{ nC}$ )
- 100% UIS tested
- RoHS compliant
- 100% EAS Tested

$V_{DS}$	650	V
$R_{DS(on),TYP} @ V_{GS}=10 \text{ V}$	640	$\text{m}\Omega$
$I_D$	12	A

TO-220F



Part ID	Package Type	Marking	Packing
ZT12N65F	TO-220F	ZT12N65F	1000pcs/Tape

**Absolute Maximum Ratings  $T_A = 25^\circ\text{C}$ , unless otherwise specified**

Symbol	Parameter	Rating	Unit	
<b>Common Ratings (<math>T_c=25^\circ\text{C}</math> Unless Otherwise Noted)</b>				
$V_{GS}$	Gate-Source Voltage	$\pm 30$	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	650	V	
$T_J$	Maximum Junction Temperature	150	$^\circ\text{C}$	
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$	
$I_{DM}$	Drain Current-Continuous@ Current-Pulsed (Note 1)	$T_c=25^\circ\text{C}$	48	A

### Mounted on Large Heat Sink

$I_D$	Drain Current-Continuous	$T_c=25^\circ\text{C}$	12	A
		$T_c=100^\circ\text{C}$	7.5	A
$P_D$	Maximum Power Dissipation		42	W
	Derate above $25^\circ\text{C}$		0.34	$\text{W}/^\circ\text{C}$
$R_{\theta JC}$	Thermal Resistance-Junction to Case		2.98	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		110	$^\circ\text{C}/\text{W}$

### Drain-Source Avalanche Ratings

EAS	Avalanche Energy, Single Pulsed (Note 2)	500	mJ
dv/dt	Reverse Diode dv/dt (Note 3)	5	V/ns



**Electrical Characteristics ( $T_j=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ <math>T_j=25^\circ\text{C}</math> (unless otherwise stated)</b>						
V(BR)DSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	650	--	--	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=650\text{V}, V_{GS}=0\text{V}$	--	--	1	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS}=\pm 30\text{V}, V_{DS}=0\text{V}$	--	--	$\pm 100$	nA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2.0	--	4.0	V
$R_{DS(\text{on})}$	Drain-Source On-State Resistance	$V_{GS}=10\text{V}, I_D=6\text{A}$	--	640	800	$\text{m}\Omega$
<b>Dynamic Electrical Characteristics @ <math>T_j = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
C <sub>iss</sub>	Input Capacitance	$V_{DS}=25\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	--	1998	--	pF
C <sub>oss</sub>	OutputCapacitance		--	162	--	pF
C <sub>rss</sub>	ReverseTransferCapacitance		--	7.3	--	pF
Q <sub>g</sub>	Total Gate Charge	$V_{DD}=520\text{V}, I_D=12\text{A}, V_{GS}=0\text{to}10\text{V}$	--	41.9	--	nC
Q <sub>gs</sub>	Gate-SourceCharge		--	10.8	--	nC
Q <sub>gd</sub>	Gate-DrainCharge		--	15	--	nC
V <sub>plateau</sub>	Gate plateau voltage		--	5	--	V
<b>Switching Characteristics (Note 2)</b>						
T <sub>d(on)</sub>	Turn-on Delay Time	$V_{DD}=325\text{V}, I_D = 12\text{A}, R_G=10\Omega, V_{GS}=15\text{V}$	--	14.5	--	ns
T <sub>r</sub>	Turn-on Rise Time		--	37.6	--	ns
T <sub>d(off)</sub>	Turn-Off Delay Time		--	69	--	ns
T <sub>f</sub>	Turn-Off Fall Time		--	16	--	ns
<b>Source- Drain Diode Characteristics@ <math>T_j = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
V <sub>SD</sub>	Forward on voltage	$I_F=12\text{A}, V_{GS}=0\text{V}$	--	--	1.5	V
T <sub>rr</sub>	Reverse Recovery Time	$T_j=25^\circ\text{C}, I_F = 12\text{A}, V_R = 325\text{V}$ $di/dt=100\text{A}/\mu\text{s}$	--	450.4	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge		--	4.75	--	nC
I <sub>rrm</sub>	Peak Reverse Recovery Current		--	21.1	--	A

Notes:

1. Pulse width limited by maximum junction temperature.
2. L=10mH,  $I_{AS} = 10\text{A}$ , Starting  $T_j = 25^\circ\text{C}$ .
3.  $I_{SD} = 12\text{A}$ ,  $di/dt \leq 100\text{A}/\mu\text{s}$ ,  $V_{DD} \leq BV_{DS}$ , Starting  $T_j = 25^\circ\text{C}$ .

### Electrical Characteristics Diagrams

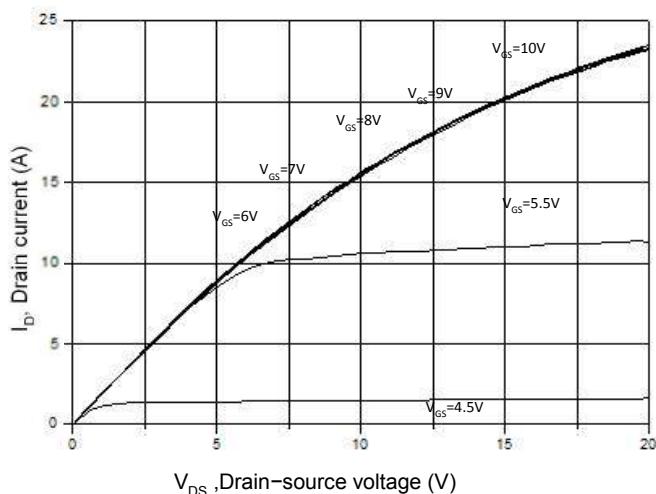


Figure 1. Typical Output Characteristics

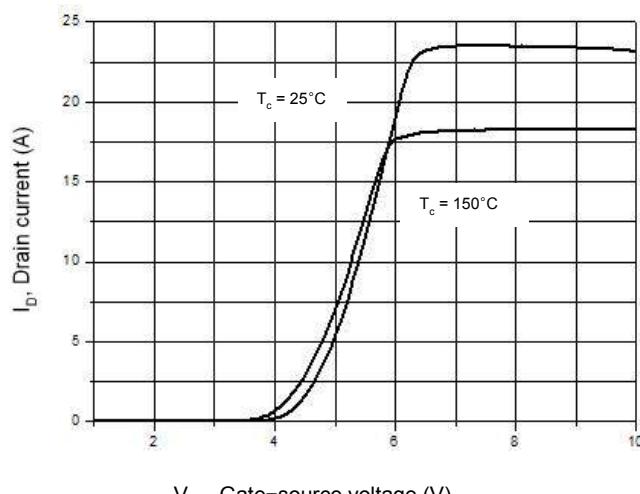


Figure 2. Transfer Characteristics

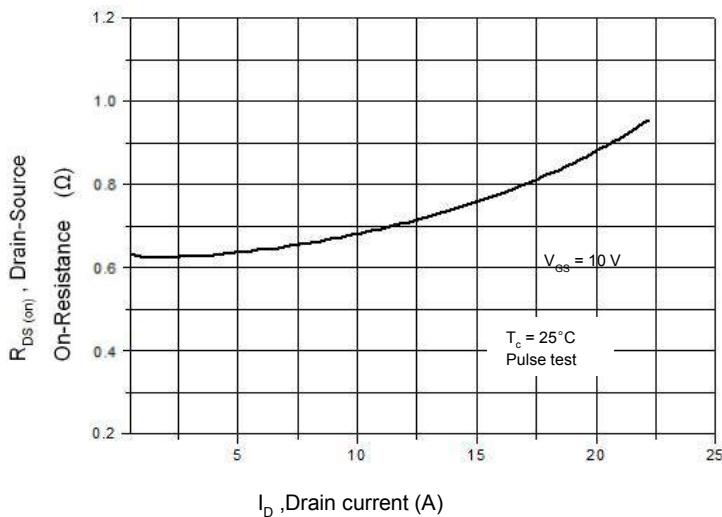


Figure 3. On-Resistance Variation vs. Drain Current

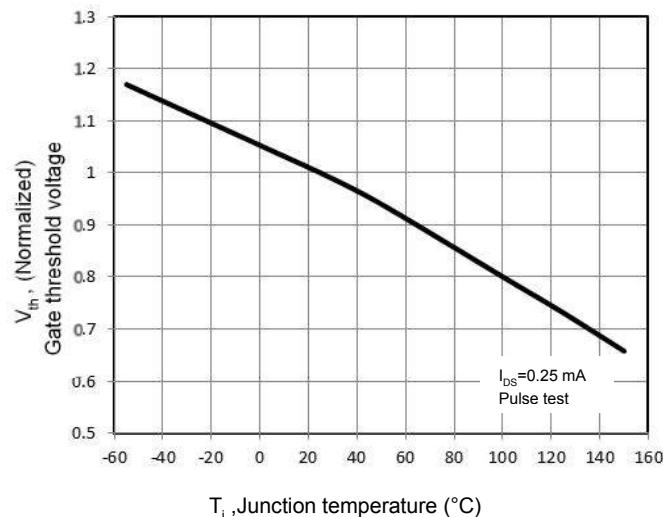


Figure 4. Threshold Voltage vs. Temperature

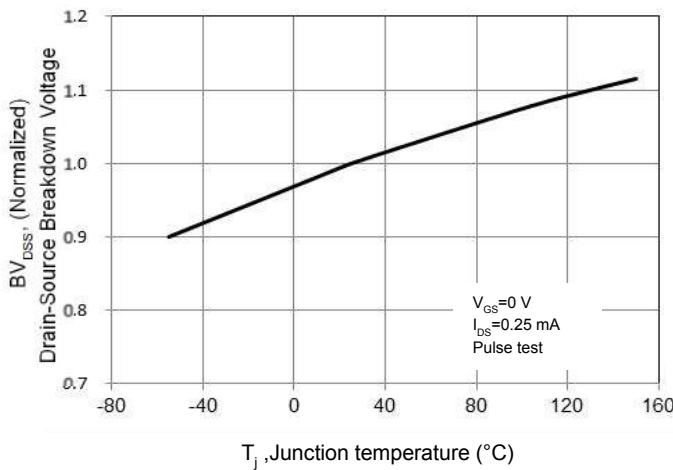


Figure 5. Breakdown Voltage vs. Temperature

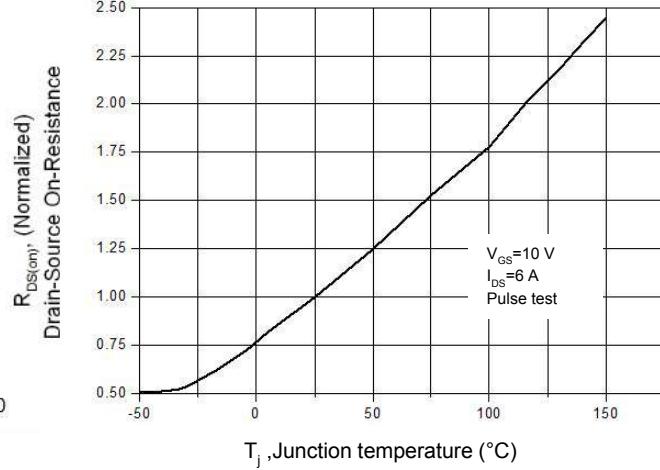


Figure 6. On-Resistance vs. Temperature

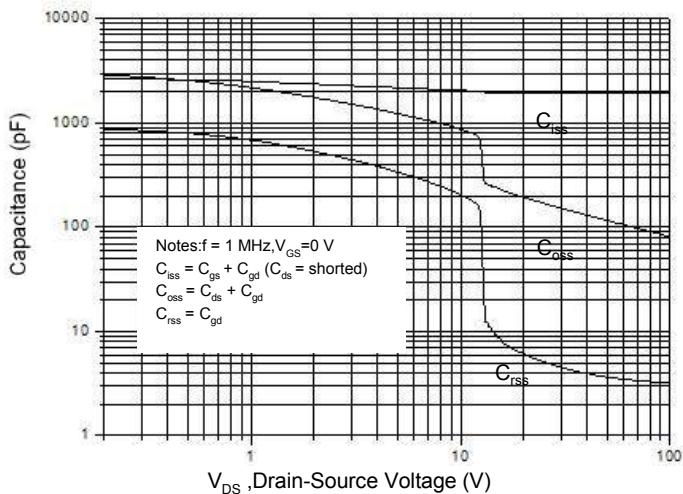


Figure 7. Capacitance Characteristics

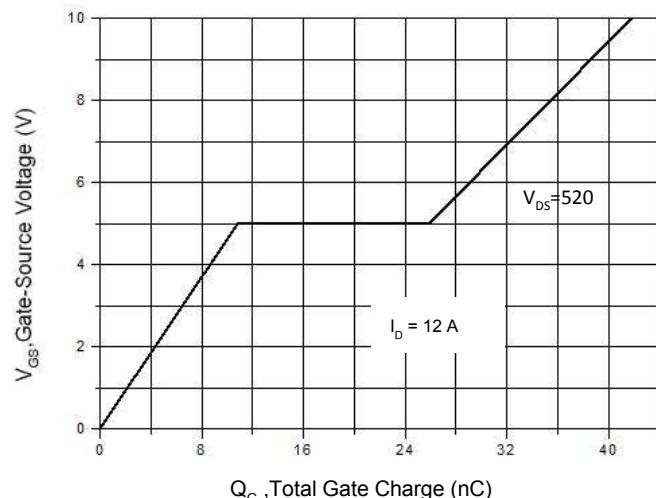


Figure 8. Gate Charge Characteristics

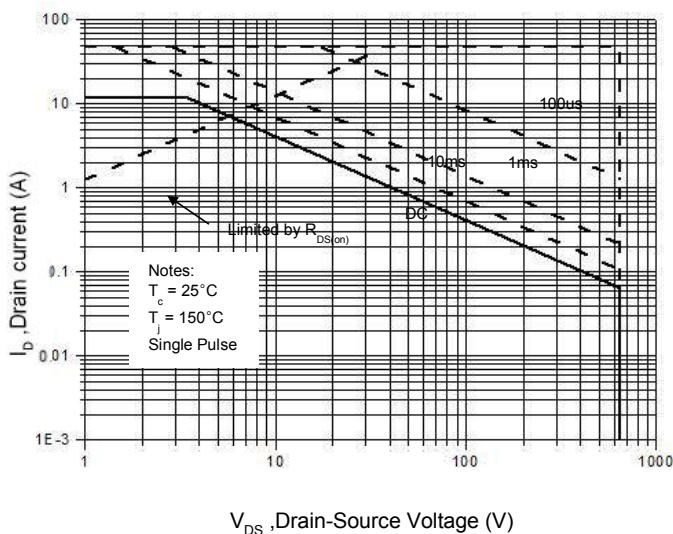


Figure 9. Maximum Safe Operating Area

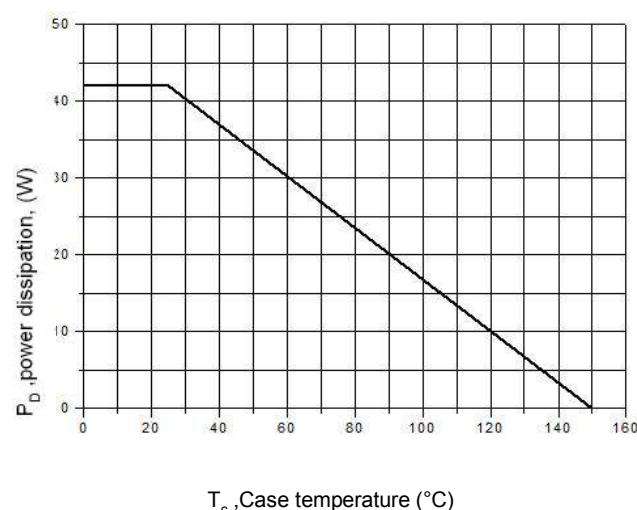


Figure 10. Power Dissipation vs. Temperature

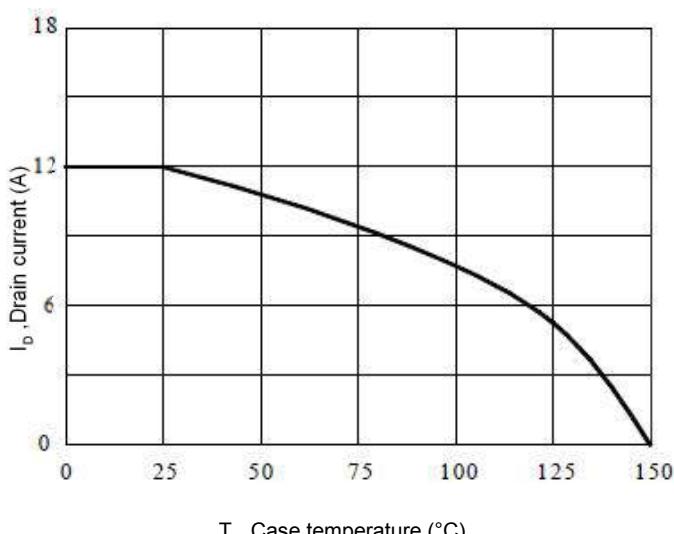


Figure 11. Continuous Drain Current vs. Temperature

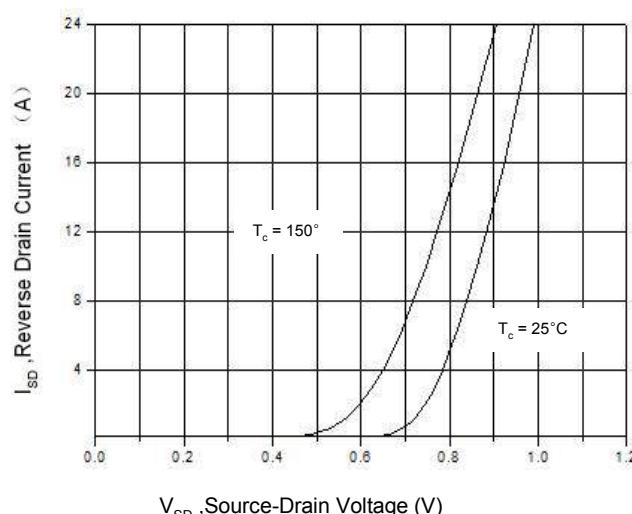


Figure 12. Body Diode Transfer Characteristics

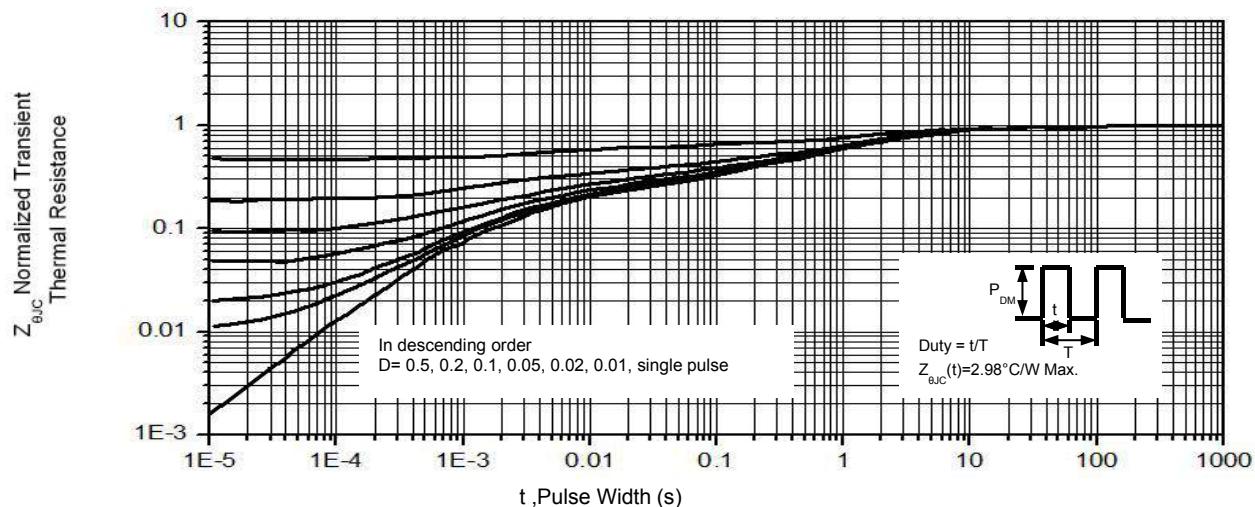
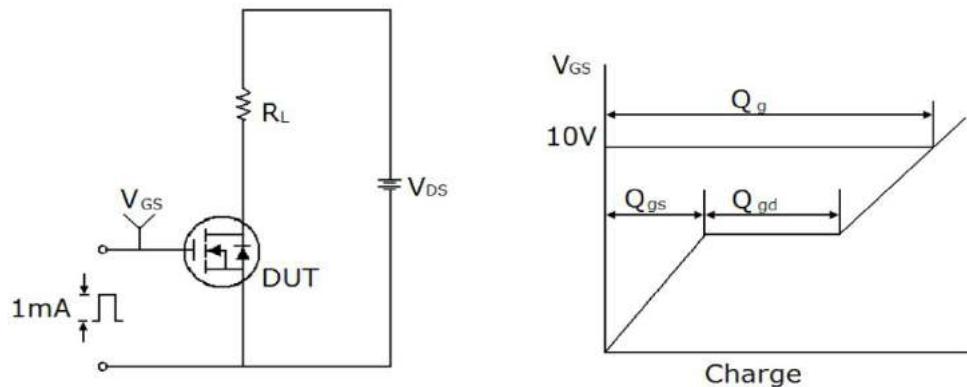


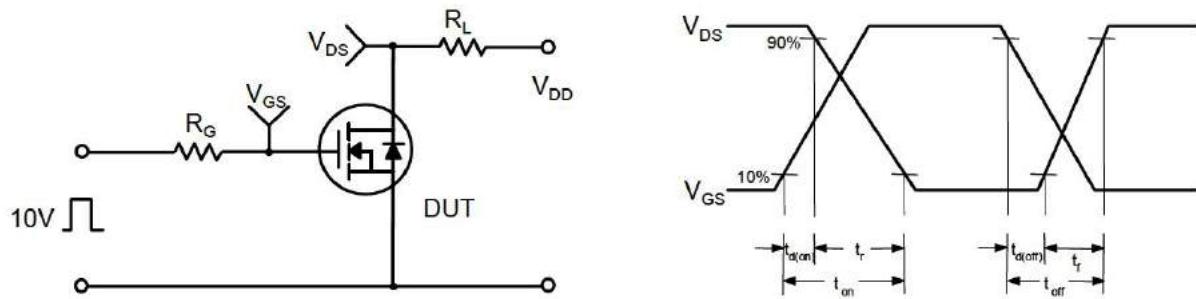
Figure 13 Transient Thermal Impedance, Junction to Case



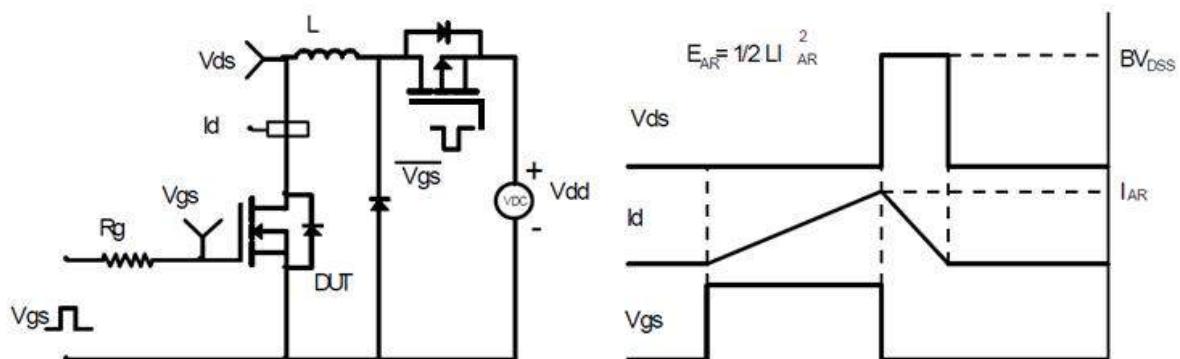
### Gate Charge Test Circuit & Waveform



### Switching Test Circuit & Waveforms

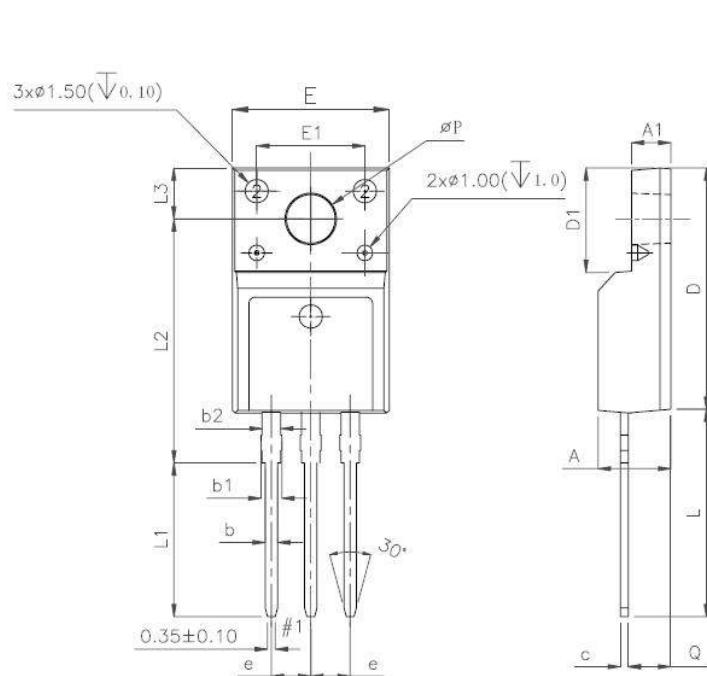


### Unclamped Inductive Switching Test Circuit & Waveforms





Mechanical Dimensions for TO-220F



UNIT: mm			
SYMBOL	MIN	NOM	MAX
A	4.5		4.9
A1	2.3		2.9
b	0.65		0.9
b1	1.1		1.7
b2	1.2		1.4
c	0.35		0.65
D	14.5		16.5
D1	6.1		6.9
E	9.6		10.3
E1	6.5	7	7.5
e	2.44	2.54	2.64
L	12.5		14.3
L1	9.45		10.05
L2	15		16
L3	3.2		4.4
ØP	3		3.3
Q	2.5		2.9

## Customer Service

### Sales and Service:

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